

GCA AS200 Autostep

The AS200 stepper is an I-line 5x reduction stepper that is capable of submicron resolution with high accuracy alignment. It can accommodate wafer sizes of 1cm pieces to 6" wafers and has automated 4" wafer handling and alignment.

Tool Capabilities

- 5X reduction
- Min resolution $\sim .7\mu\text{m}$
- Alignment tolerance: Global alignment: $.5\mu\text{m}$, local: $.2\mu\text{m}$
- i-line 365nm UV light source
- Automatic loading 4" wafers
- Manual loading of wafers from 6" to 10x10mm
- 6" & 4" wafer thickness must be 550um
- 2" wafer thickness must be 250um
- Small pieces must be 550um thick